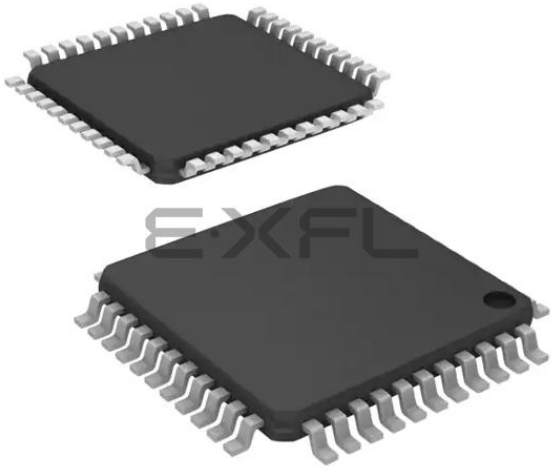

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Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx120f032dt-v-pt

TABLE 8: PIN NAMES FOR 36-PIN USB DEVICES

36-PIN VTLA (TOP VIEW)(1,2,3,5)

PIC32MX210F016C
PIC32MX220F032C
PIC32MX230F064C
PIC32MX250F128C

36

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2	19	TDO/RPB9/SDA1/CTED4/PMD3/RB9
2	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3	20	RPC9/CTED7/RC9
3	PGED4(4)/AN6/RPC0/RC0	21	VSS
4	PGEC4(4)/AN7/RPC1/RC1	22	VCAP
5	VDD	23	VDD
6	VSS	24	PGED2/RPB10/D+/CTED11/RB10
7	OSC1/CLKI/RPA2/RA2	25	PGEC2/RPB11/D-/RB11
8	OSC2/CLKO/RPA3/PMA0/RA3	26	VUSB3V3
9	SOSCI/RPB4/RB4	27	AN11/RPB13/CTPLS/PMRD/RB13
10	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	28	CVREFOUT/AN10/C3INB/RPB14/VBUSON/SCK1/CTED5/RB14
11	AN12/RPC3/RC3	29	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
12	VSS	30	AVSS
13	VDD	31	AVDD
14	VDD	32	$\overline{\text{MCLR}}$
15	TMS/RPB5/USBID/RB5	33	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0
16	VBUS	34	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1
17	TDI/RPB7/CTED3/PMD5/INT0/RB7	35	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0
18	TCK/RPB8/SCL1/CTED10/PMD4/RB8	36	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: This pin function is not available on PIC32MX210F016C and PIC32MX120F032C devices.

5: Shaded pins are 5V tolerant.

TABLE 14: PIN NAMES FOR 44-PIN USB DEVICES

44-PIN VTLA (TOP VIEW)(1,2,3,5)

PIC32MX210F016D
PIC32MX220F032D
PIC32MX230F064D
PIC32MX230F256D
PIC32MX250F128D
PIC32MX270F256D

44 1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RPB9/SDA1/CTED4/PMD3/RB9	23	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2
2	RPC6/PMA1/RC6	24	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3
3	RPC7/PMA0/RC7	25	AN6/RPC0/RC0
4	RPC8/PMA5/RC8	26	AN7/RPC1/RC1
5	RPC9/CTED7/PMA6/RC9	27	AN8/RPC2/PMA2/RC2
6	VSS	28	VDD
7	VCAP	29	VSS
8	PGED2/RPB10/D+/CTED11/RB10	30	OSC1/CLKI/RPA2/RA2
9	PGEC2/RPB11/D-/RB11	31	OSC2/CLKO/RPA3/RA3
10	VUSB3V3	32	TDO/RPA8/PMA8/RA8
11	AN11/RPB13/CTPLS/PMRD/RB13	33	SOSCI/RPB4/RB4
12	PGED4(4)/TMS/PMA10/RA10	34	SOSCO/RPA4/T1CK/CTED9/RA4
13	PGEC4(4)/TCK/CTED8/PMA7/RA7	35	TDI/RPA9/PMA9/RA9
14	CVREFOUT/AN10/C3INB/RPB14/VBUSON/SCK1/CTED5/RB14	36	AN12/RPC3/RC3
15	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15	37	RPC4/PMA4/RC4
16	AVSS	38	RPC5/PMA3/RC5
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0	41	RPB5/USBID/RB5
20	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1	42	VBUS
21	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	43	RPB7/CTED3/PMD5/INT0/RB7
22	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	44	RPB8/SCL1/CTED10/PMD4/RB8

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: This pin function is not available on PIC32MX210F016D and PIC32MX220F032D devices.

5: Shaded pins are 5V tolerant.

1.0 DEVICE OVERVIEW

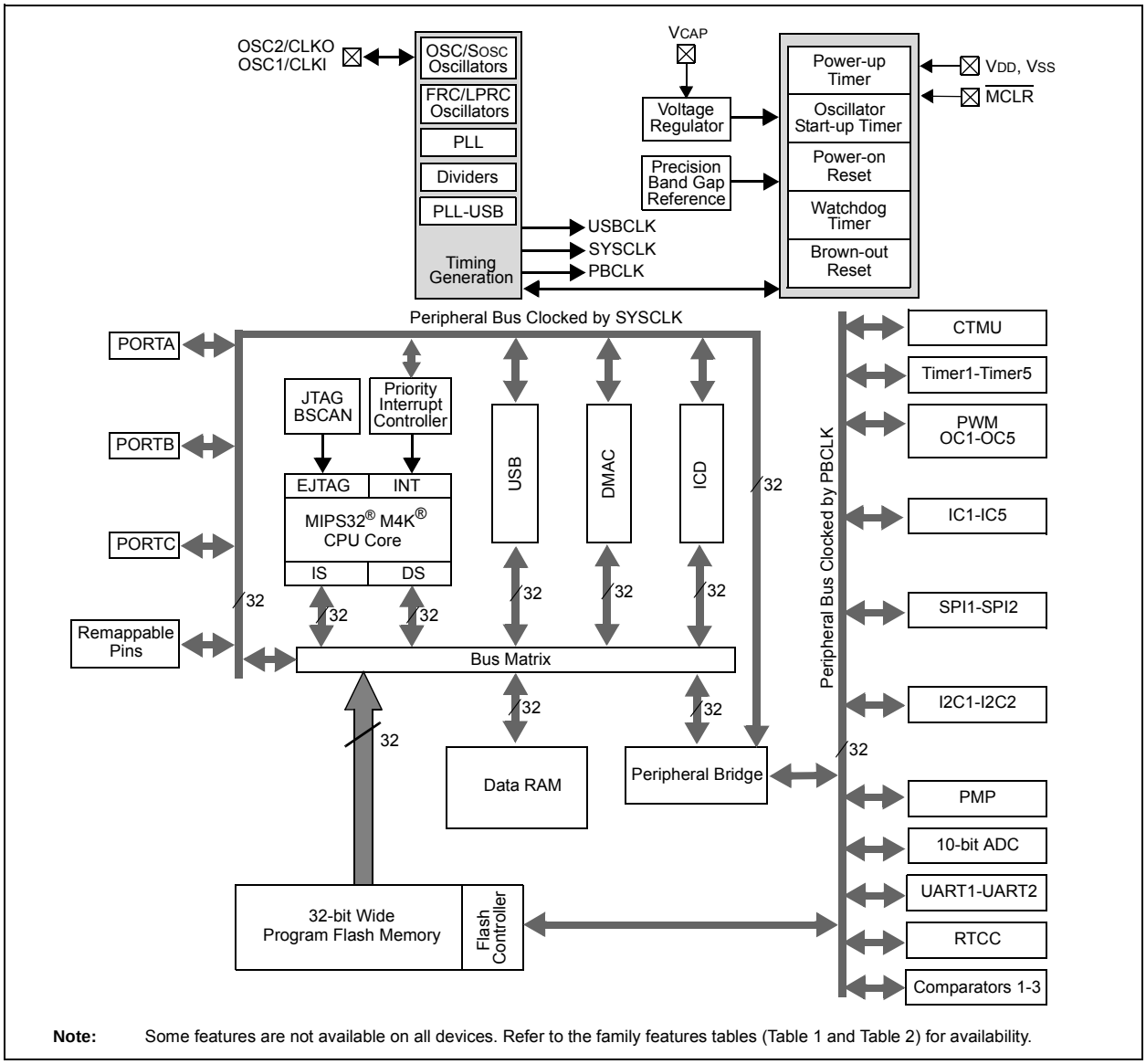
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This document contains device-specific information for PIC32MX1XX/2XX 28/36/44-pin Family devices.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the PIC32MX1XX/2XX 28/36/44-pin Family of devices.

Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: BLOCK DIAGRAM



Note: Some features are not available on all devices. Refer to the family features tables (Table 1 and Table 2) for availability.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number[1]				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
SDA1	15	18	19	1	I/O	ST	Synchronous serial data input/output for I2C1
SCL2	4	7	2	24	I/O	ST	Synchronous serial clock input/output for I2C2
SDA2	3	6	1	23	I/O	ST	Synchronous serial data input/output for I2C2
TMS	19[2] 11[3]	22[2] 14[3]	25[2] 15[3]	12	I	ST	JTAG Test mode select pin
TCK	14	17	18	13	I	ST	JTAG test clock input pin
TDI	13	16	17	35	O	—	JTAG test data input pin
TDO	15	18	19	32	O	—	JTAG test data output pin
RTCC	4	7	2	24	O	ST	Real-Time Clock alarm output
CVREF-	28	3	34	20	I	Analog	Comparator Voltage Reference (low)
CVREF+	27	2	33	19	I	Analog	Comparator Voltage Reference (high)
CVREFOUT	22	25	28	14	O	Analog	Comparator Voltage Reference output
C1INA	4	7	2	24	I	Analog	Comparator Inputs
C1INB	3	6	1	23	I	Analog	
C1INC	2	5	36	22	I	Analog	
C1IND	1	4	35	21	I	Analog	
C2INA	2	5	36	22	I	Analog	
C2INB	1	4	35	21	I	Analog	
C2INC	4	7	2	24	I	Analog	
C2IND	3	6	1	23	I	Analog	
C3INA	23	26	29	15	I	Analog	
C3INB	22	25	28	14	I	Analog	
C3INC	27	2	33	19	I	Analog	
C3IND	1	4	35	21	I	Analog	
C1OUT	PPS	PPS	PPS	PPS	O	—	Comparator Outputs
C2OUT	PPS	PPS	PPS	PPS	O	—	
C3OUT	PPS	PPS	PPS	PPS	O	—	

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

3.2 Architecture Overview

The MIPS32 M4K processor core contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e® Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32 M4K processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32 M4K processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown ('32' of 32x16) represents the *rs* operand. The second number ('16' of 32x16) represents the *rt* operand. The PIC32 core only checks the value of the latter (*rt)* operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

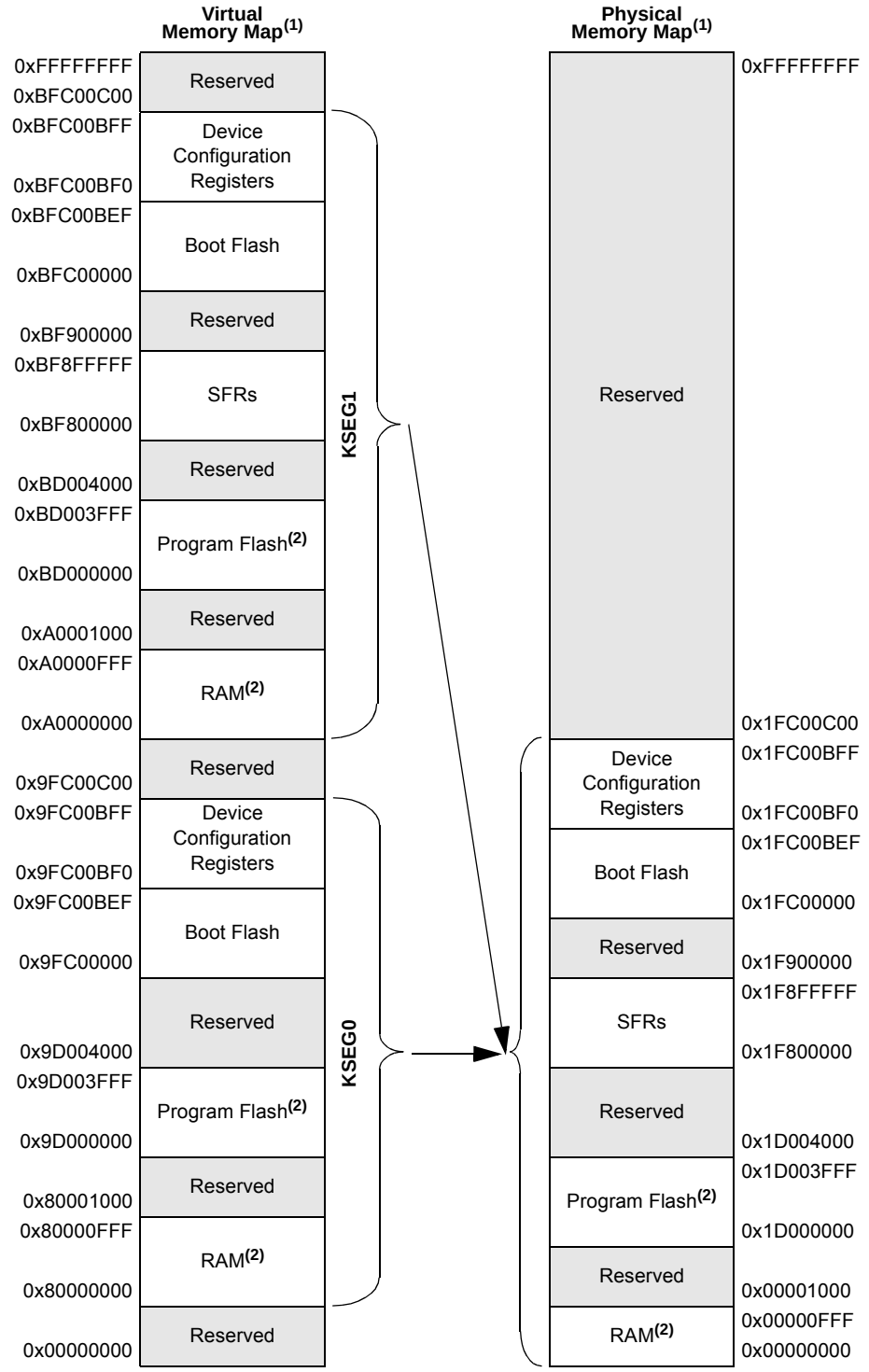
Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32 core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU, MADD/MADDU, MSUB/MSUBU`	16 bits	1	1
	32 bits	2	2
`MUL`	16 bits	2	1
	32 bits	3	2
`DIV/DIVU`	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

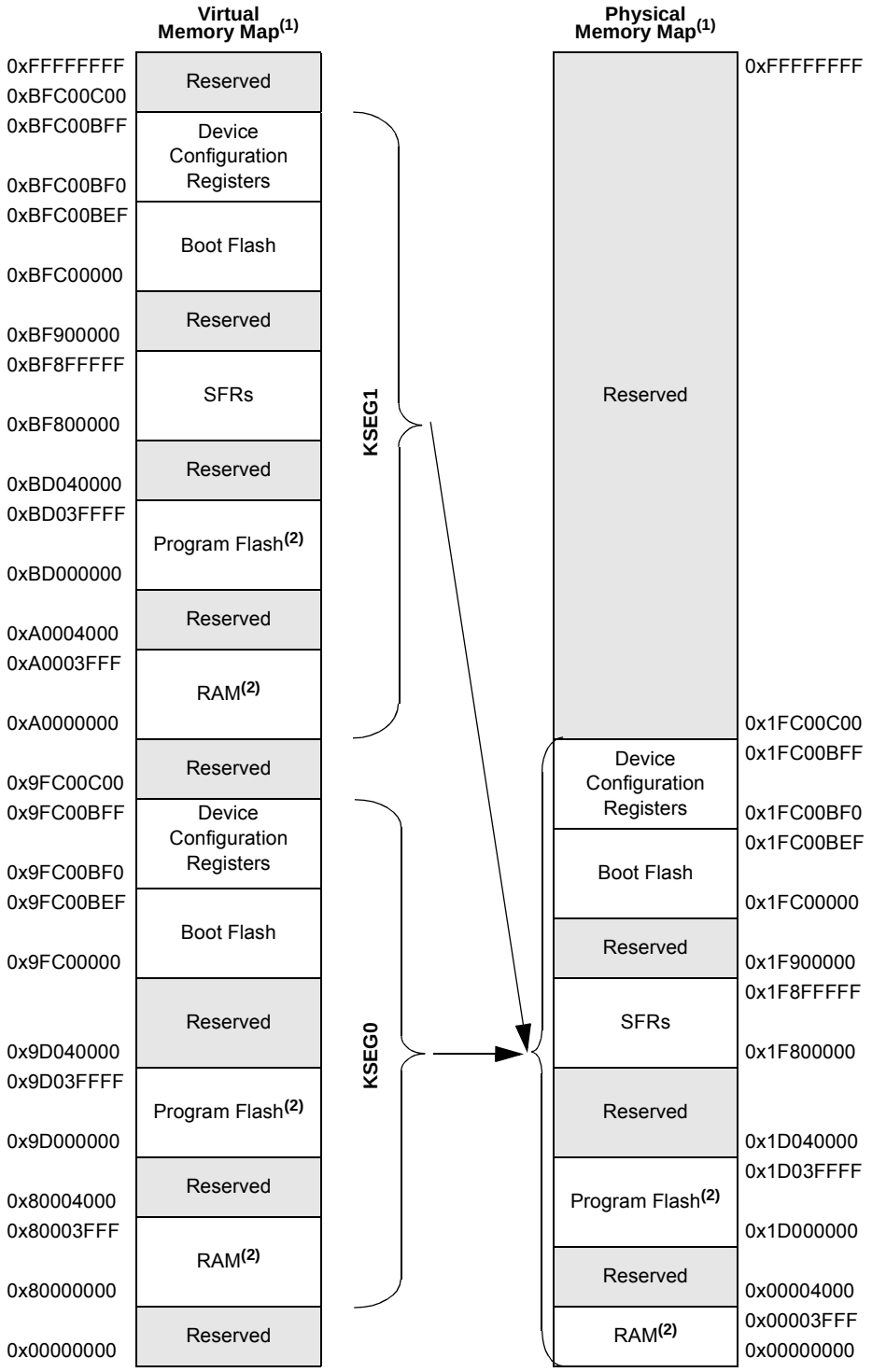
FIGURE 4-1: MEMORY MAP ON RESET FOR PIC32MX110/210 DEVICES (4 KB RAM, 16 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

FIGURE 4-6: MEMORY MAP ON RESET FOR PIC32MX130/230 DEVICES (16 KB RAM, 256 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

8.0 OSCILLATOR CONFIGURATION

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 6. "Oscillator Configuration"** (DS60001112), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32MX1XX/2XX 28/36/44-pin Family oscillator system has the following modules and features:

- Four external and internal oscillator options as clock sources
- On-Chip PLL with user-selectable input divider, multiplier and output divider to boost operating frequency on select internal and external oscillator sources
- On-Chip user-selectable divisor postscaler on select oscillator sources
- Software-controllable switching between various clock sources
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Dedicated On-Chip PLL for USB peripheral

A block diagram of the oscillator system is provided in Figure 8-1.

TABLE 9-3: DMA CHANNELS 0-3 REGISTER MAP (CONTINUED)

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3170	DCH1SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSSIZ<15:0>																0000
3180	DCH1DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDSIZ<15:0>																0000
3190	DCH1SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSPTR<15:0>																0000
31A0	DCH1DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDPTR<15:0>																0000
31B0	DCH1CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCSIZ<15:0>																0000
31C0	DCH1CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCPTR<15:0>																0000
31D0	DCH1DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHPDAT<7:0>								0000
31E0	DCH2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHBUSY	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>		0000
31F0	DCH2ECON	31:16	—	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FF00
3200	DCH2INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
3210	DCH2SSA	31:16	CHSSA<31:0>																0000
		15:0																	0000
3220	DCH2DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
3230	DCH2SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSSIZ<15:0>																0000
3240	DCH2DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDSIZ<15:0>																0000
3250	DCH2SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSPTR<15:0>																0000
3260	DCH2DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDPTR<15:0>																0000
3270	DCH2CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCSIZ<15:0>																0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

NOTES:

11.3 Peripheral Pin Select

A major challenge in general purpose devices is providing the largest possible set of peripheral features while minimizing the conflict of features on I/O pins. The challenge is even greater on low pin-count devices. In an application where more than one peripheral needs to be assigned to a single pin, inconvenient workarounds in application code or a complete redesign may be the only option.

The Peripheral Pin Select (PPS) configuration provides an alternative to these choices by enabling peripheral set selection and their placement on a wide range of I/O pins. By increasing the pinout options available on a particular device, users can better tailor the device to their entire application, rather than trimming the application to fit the device.

The PPS configuration feature operates over a fixed subset of digital I/O pins. Users may independently map the input and/or output of most digital peripherals to these I/O pins. PPS is performed in software and generally does not require the device to be reprogrammed. Hardware safeguards are included that prevent accidental or spurious changes to the peripheral mapping once it has been established.

11.3.1 AVAILABLE PINS

The number of available pins is dependent on the particular device and its pin count. Pins that support the PPS feature include the designation “RPn” in their full pin designation, where “RP” designates a remappable peripheral and “n” is the remappable port number.

11.3.2 AVAILABLE PERIPHERALS

The peripherals managed by the PPS are all digital-only peripherals. These include general serial communications (UART and SPI), general purpose timer clock inputs, timer-related peripherals (input capture and output compare) and interrupt-on-change inputs.

In comparison, some digital-only peripheral modules are never included in the PPS feature. This is because the peripheral’s function requires special I/O circuitry on a specific port and cannot be easily connected to multiple pins. These modules include I^2C among others. A similar requirement excludes all modules with analog inputs, such as the Analog-to-Digital Converter (ADC).

A key difference between remappable and non-remappable peripherals is that remappable peripherals are not associated with a default I/O pin. The peripheral must always be assigned to a specific I/O pin before it can be used. In contrast, non-remappable peripherals are always available on a default pin, assuming that the peripheral is active and not conflicting with another peripheral.

When a remappable peripheral is active on a given I/O pin, it takes priority over all other digital I/O and digital communication peripherals associated with the pin. Priority is given regardless of the type of peripheral that is mapped. Remappable peripherals never take priority over any analog functions associated with the pin.

11.3.3 CONTROLLING PERIPHERAL PIN SELECT

PPS features are controlled through two sets of SFRs: one to map peripheral inputs, and one to map outputs. Because they are separately controlled, a particular peripheral’s input and output (if the peripheral has both) can be placed on any selectable function pin without constraint.

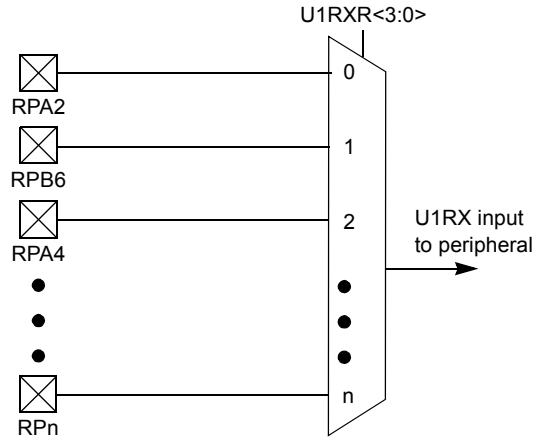
The association of a peripheral to a peripheral-selectable pin is handled in two different ways, depending on whether an input or output is being mapped.

11.3.4 INPUT MAPPING

The inputs of the PPS options are mapped on the basis of the peripheral. That is, a control register associated with a peripheral dictates the pin it will be mapped to. The [*pin name*]R registers, where [*pin name*] refers to the peripheral pins listed in Table 11-1, are used to configure peripheral input mapping (see Register 11-1). Each register contains sets of 4 bit fields. Programming these bit fields with an appropriate value maps the RPn pin with the corresponding value to that peripheral. For any given device, the valid range of values for any bit field is shown in Table 11-1.

For example, Figure 11-2 illustrates the remappable pin selection for the U1RX input.

FIGURE 11-2: REMAPPABLE INPUT EXAMPLE FOR U1RX



Note: For input only, PPS functionality does not have priority over TRISx settings. Therefore, when configuring RPn pin for input, the corresponding bit in the TRISx register must also be configured for input (set to ‘1’).

NOTES:

REGISTER 20-3: PMADDR: PARALLEL PORT ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	—	CS1(1) / ADDR14(2)	—	—	—	ADDR<10:8>		
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-15 **Unimplemented:** Read as '0'

bit 14 **CS1:** Chip Select 1 bit(1)
- 1 = Chip Select 1 is active
- 0 = Chip Select 1 is inactive

bit 14 **ADDR<14>:** Destination Address bit 14(2)

bit 13-11 **Unimplemented:** Read as '0'

bit 10-0 **ADDR<10:0>:** Destination Address bits

Note 1: When the CSF<1:0> bits (PMCON<7:6>) = 10.

2: When the CSF<1:0> bits (PMCON<7:6>) = 00 or 01.

NOTES:

REGISTER 27-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 18-10 **PWP<8:0>:** Program Flash Write-Protect bits(3)

Prevents selected program Flash memory pages from being modified during code execution.
111111111 = Disabled
111111110 = Memory below 0x0400 address is write-protected
111111101 = Memory below 0x0800 address is write-protected
111111100 = Memory below 0x0C00 address is write-protected
111111011 = Memory below 0x1000 (4K) address is write-protected
111111010 = Memory below 0x1400 address is write-protected
111111001 = Memory below 0x1800 address is write-protected
111111000 = Memory below 0x1C00 address is write-protected
111110111 = Memory below 0x2000 (8K) address is write-protected
111110110 = Memory below 0x2400 address is write-protected
111110101 = Memory below 0x2800 address is write-protected
111110100 = Memory below 0x2C00 address is write-protected
111110011 = Memory below 0x3000 address is write-protected
111110010 = Memory below 0x3400 address is write-protected
111110001 = Memory below 0x3800 address is write-protected
111110000 = Memory below 0x3C00 address is write-protected
111101111 = Memory below 0x4000 (16K) address is write-protected
.
.
.
110111111 = Memory below 0x10000 (64K) address is write-protected
.
.
.
101111111 = Memory below 0x20000 (128K) address is write-protected
.
.
.
011111111 = Memory below 0x40000 (256K) address is write-protected
.
.
.
000000000 = All possible memory is write-protected

bit 9-5 **Reserved:** Write '1'

bit 4-3 **ICESEL<1:0>:** In-Circuit Emulator/Debugger Communication Channel Select bits(2)

11 = PGEC1/PGED1 pair is used
10 = PGEC2/PGED2 pair is used
01 = PGEC3/PGED3 pair is used
00 = PGEC4/PGED4 pair is used(2)

bit 2 **JTAGEN:** JTAG Enable bit(1)

1 = JTAG is enabled
0 = JTAG is disabled

bit 1-0 **DEBUG<1:0>:** Background Debugger Enable bits (forced to '11' if code-protect is enabled)

1x = Debugger is disabled
0x = Debugger is enabled

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

2: The PGEC4/PGED4 pin pair is not available on all devices. Refer to the **"Pin Diagrams"** section for availability.

3: The PWP<8:7> bits are only available on devices with 256 KB Flash.

TABLE 30-18: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	3.92	—	5	MHz	ECPLL, HSPLL, XTPLL, FRCPLL modes
OS51	FSYS	On-Chip VCO System Frequency	60	—	120	MHz	—
OS52	TLOCK	PLL Start-up Time (Lock Time)	—	—	2	ms	—
OS53	DCLK	CLKO Stability(2) (Period Jitter or Cumulative)	-0.25	—	+0.25	%	Measured over 100 ms period

Note 1: These parameters are characterized, but not tested in manufacturing.

2: This jitter specification is based on clock-cycle by clock-cycle measurements. To get the effective jitter for individual time-bases on communication clocks, use the following formula:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{SYSCLK}{CommunicationClock}}}$$

For example, if SYSCLK = 40 MHz and SPI bit rate = 20 MHz, the effective jitter is as follows:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{40}{20}}} = \frac{D_{CLK}}{1.41}$$

TABLE 30-19: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
Internal FRC Accuracy @ 8.00 MHz(1)						
F20b	FRC	-0.9	—	+0.9	%	—

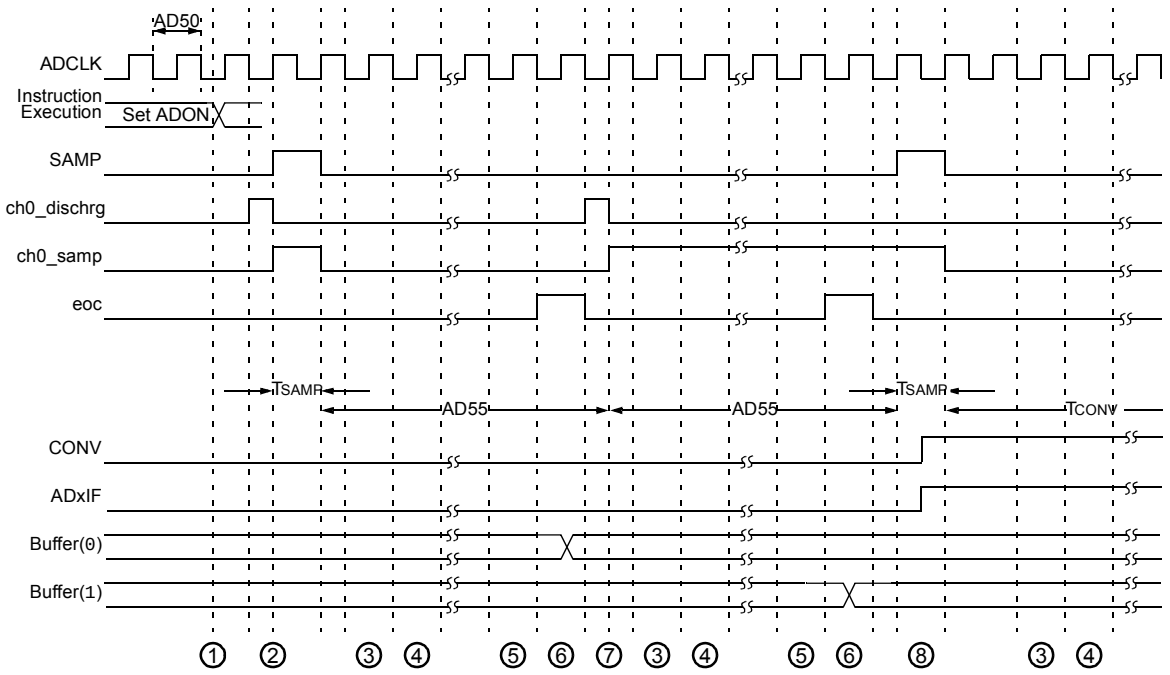
Note 1: Frequency calibrated at 25°C and 3.3V. The TUN bits can be used to compensate for temperature drift.

TABLE 30-20: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
LPRC @ 31.25 kHz(1)						
F21	LPRC	-15	—	+15	%	—

Note 1: Change of LPRC frequency as VDD changes.

FIGURE 30-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



(1) – Software sets ADxCON. ADON to start AD operation.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104).

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

(6) – One TAD for end of conversion.

(7) – Begin conversion of next channel.

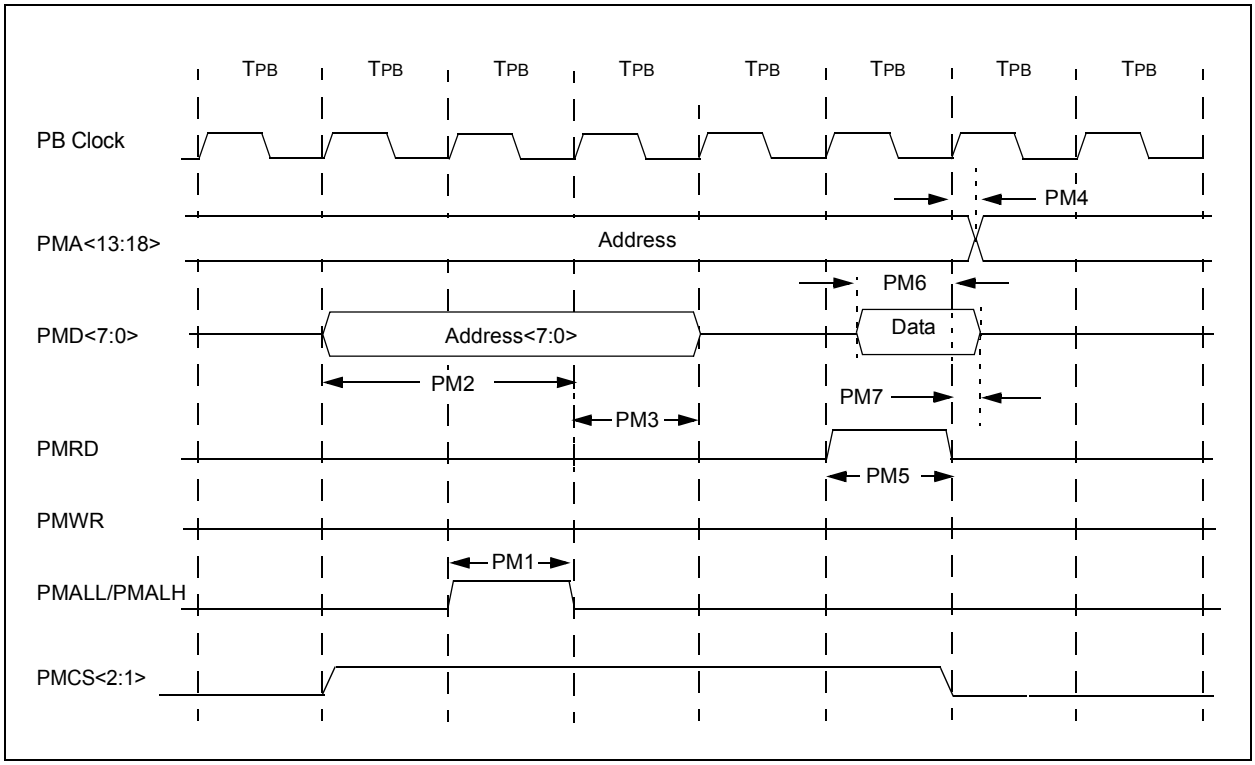
(8) – Sample for time specified by SAMC<4:0>.

TABLE 30-37: PARALLEL SLAVE PORT REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param.No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
PS1	TdtV2wrH	Data In Valid before $\overline{WR}$ or $\overline{CS}$ Inactive (setup time)	20	—	—	ns	—
PS2	TwrH2dtI	$\overline{WR}$ or $\overline{CS}$ Inactive to Data-In Invalid (hold time)	40	—	—	ns	—
PS3	TrdL2dtV	$\overline{RD}$ and $\overline{CS}$ Active to Data-Out Valid	—	—	60	ns	—
PS4	TrdH2dtI	$\overline{RD}$ Active or $\overline{CS}$ Inactive to Data-Out Invalid	0	—	10	ns	—
PS5	Tcs	$\overline{CS}$ Active Time	TPB + 40	—	—	ns	—
PS6	TWR	$\overline{WR}$ Active Time	TPB + 25	—	—	ns	—
PS7	TRD	$\overline{RD}$ Active Time	TPB + 25	—	—	ns	—

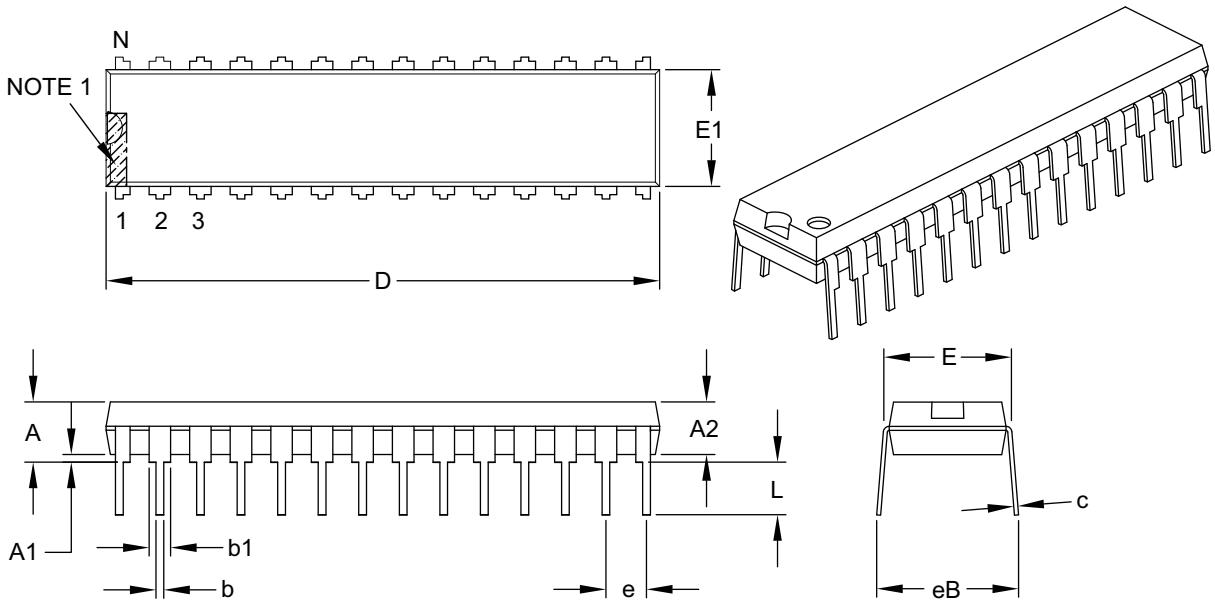
Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-21: PARALLEL MASTER PORT READ TIMING DIAGRAM



28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

Revision G (April 2015)

This revision includes the addition of the following devices:

- PIC32MX130F256B
- PIC32MX230F256B
- PIC32MX130F256D
- PIC32MX230F256D

The title of the document was updated to avoid confusion with the PIC32MX1XX/2XX/5XX 64/100-pin Family data sheet.

All peripheral SFR maps have been relocated from the Memory chapter to their respective peripheral chapters.

In addition, this revision includes the following major changes as described in Table A-6, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-6: MAJOR SECTION UPDATES

Section	Update Description
32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog	Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see Pin Diagrams).
2.0 "Guidelines for Getting Started with 32-bit MCUs"	Updated these sections: **2.2 "Decoupling Capacitors"**, **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**, **2.4 "Master Clear (MCLR) Pin"**, **2.8.1 "Crystal Oscillator Design Consideration"**
4.0 "Memory Organization"	Added Memory Map for new devices (see Figure 4-6).
14.0 "Watchdog Timer (WDT)"	New chapter created from content previously located in the Special Features chapter.
30.0 "Electrical Characteristics"	Removed parameter D312 (TSET) from the Comparator Specifications (see Table 30-12). Added the Comparator Voltage Reference Specifications (see Table 30-13). Updated Table 30-12.

Revision H (July 2015)

This revision includes the following major changes as described in Table A-7, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-7: MAJOR SECTION UPDATES

Section	Update Description
2.0 "Guidelines for Getting Started with 32-bit MCUs"	**Section 2.9 "Sosc Design Recommendation"** was removed.
8.0 "Oscillator Configuration"	The Primary Oscillator (POSC) logic in the Oscillator diagram was updated (see Figure 8-1).
30.0 "Electrical Characteristics"	The Power-Down Current (IPD) DC Characteristics parameter DC40k was updated (see Table 30-7). **Table 30-9: "DC Characteristics: I/O Pin Input Injection current Specifications"** was added.